CAT660

100 mA CMOS Charge Pump Inverter/Doubler

Description

The CAT660 is a charge-pump voltage converter. It will invert a 1.5 V to 5.5 V input to a −1.5 V to −5.5 V output. Only two external capacitors are needed. With a guaranteed 100 mA output current capability, the CAT660 can replace a switching regulator and its inductor. Lower EMI is achieved due to the absence of an inductor.

In addition, the CAT660 can double a voltage supplied from a battery or power supply. Inputs from 2.5 V to 5.5 V will yield a doubled, 5 V to 11 V output voltage.

A Frequency Control pin (BOOST/FC) is provided to select either a high (80 kHz) or low (10 kHz) internal oscillator frequency, thus allowing quiescent current vs. capacitor size trade-offs to be made. The 80 kHz frequency is selected when the FC pin is connected to V+.

The operating frequency can also be adjusted with an external capacitor at the OSC pin or by driving OSC with an external clock.

8-pin SOIC package is available in the industrial temperature range.

The CAT660 replaces the MAX660 and the LTC®660. In addition, the CAT660 is pin compatible with the 7660/1044, offering an easy upgrade for applications with 100 mA loads.

Features

- Replaces MAX660 and LTC®660
- Converts V+ to V− or V+ to 2V+
- Low Output Resistance, 4 Ω Typical
- High Power Efficiency
- Selectable Charge Pump Frequency
  - 10 kHz or 80 kHz
  - Optimize Capacitor Size
- Low Quiescent Current
- Pin–compatible, High–current Alternative to 7660/1044
- Industrial Temperature Range
- Available in 8-pin SOIC Package
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

- Negative Voltage Generator
- Voltage Doubler
- Voltage Splitter
- Low EMI Power Source
- GaAs FET Biasing
- Lithium Battery Power Supply
- Instrumentation
- LCD Contrast Bias
- Cellular Phones, Pagers

ON Semiconductor®

http://onsemi.com

PIN CONFIGURATION

SOIC–8
V SUFFIX
CASE 751BD
(Top View)

V+ OSC LV OUT
BOOST/FC CAP+
GND CAP−

MARKING DIAGRAMS

CAT660EVA = CAT660EVA–GT3

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Device</th>
<th>Package</th>
<th>Shipping</th>
</tr>
</thead>
<tbody>
<tr>
<td>CAT660EVA–GT3</td>
<td>SOIC–8</td>
<td>3,000 /</td>
</tr>
<tr>
<td></td>
<td>(Pb–Free)</td>
<td>Tape &amp; Reel</td>
</tr>
</tbody>
</table>

1. All packages are RoHS–compliant (Lead–free, Halogen–free).
2. For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.
3. For detailed information and a breakdown of device nomenclature and numbering systems, please see the ON Semiconductor Device Nomenclature document, TND310/D, available at www.onsemi.com
Typical Application

Figure 1. Voltage Inverter

C1
1 µF to 150 µF
1
2
3
4
5
6
7
8

1
BOOST/FC
V+
CAP+
OSC
CAT660
GND
LV
CAP–
OUT
+V\text{IN}
1.5 V to 5.5 V

V+
OSC
LV
OUT
C1
1 µF to 150 µF
1
2
3
4
5
6
7
8

1
BOOST/FC
V+
CAP+
OSC
CAT660
GND
LV
CAP–
OUT
V\text{IN} = 2.5 V to 5.5 V

Figure 2. Positive Voltage Doubler

C2
1 µF to 150 µF
1
2
3
4
5
6
7
8

1
BOOST/FC
V+
CAP+
OSC
CAT660
GND
LV
CAP–
OUT

Table 1. PIN DESCRIPTIONS

<table>
<thead>
<tr>
<th>Pin Number</th>
<th>Name</th>
<th>Circuit Configuration</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td></td>
<td>Inverter Mode</td>
</tr>
<tr>
<td>1</td>
<td>Boost/FC</td>
<td>Frequency Control for the internal oscillator. With an external oscillator Boost/FC has no effect.</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Boost/FC</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Open</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V+</td>
</tr>
<tr>
<td>2</td>
<td>CAP+</td>
<td>Charge pump capacitor. Positive terminal.</td>
</tr>
<tr>
<td>3</td>
<td>GND</td>
<td>Power supply ground.</td>
</tr>
<tr>
<td>4</td>
<td>CAP–</td>
<td>Charge pump capacitor. Negative terminal.</td>
</tr>
<tr>
<td>5</td>
<td>OUT</td>
<td>Output for negative voltage.</td>
</tr>
<tr>
<td>6</td>
<td>LV</td>
<td>Low-Voltage selection pin. When the input voltage is less than 3 V, connect LV to GND. For input voltages above 3 V, LV may be connected to GND or left open. If OSC is driven externally, connect LV to GND.</td>
</tr>
<tr>
<td>7</td>
<td>OSC</td>
<td>Oscillator control input. An external capacitor can be connected to lower the oscillator frequency. An external oscillator can drive OSC and set the chip operating frequency. The charge-pump frequency is one-half the frequency at OSC.</td>
</tr>
</tbody>
</table>
Table 2. ABSOLUTE MAXIMUM RATINGS

<table>
<thead>
<tr>
<th>Parameters</th>
<th>Ratings</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>V+ to GND</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Input Voltage (Pins 1, 6 and 7)</td>
<td>−0.3 to (V+ + 0.3)</td>
<td>V</td>
</tr>
<tr>
<td>BOOST/FC and OSC Input Voltage</td>
<td>The least negative of (Out – 0.3 V) or (V+ − 6 V) to (V+ + 0.3 V)</td>
<td>V</td>
</tr>
<tr>
<td>Output Short-circuit Duration to GND (OUT may be shorted to GND for 1 sec without damage but shorting OUT to V+ should be avoided.)</td>
<td>1</td>
<td>sec.</td>
</tr>
<tr>
<td>Continuous Power Dissipation (TA = 70°C)</td>
<td>Plastic DIP</td>
<td></td>
</tr>
<tr>
<td>PLastic DIP</td>
<td>730</td>
<td>mW</td>
</tr>
<tr>
<td>SOIC</td>
<td>500</td>
<td>mW</td>
</tr>
<tr>
<td>TDFN</td>
<td>1</td>
<td>W</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>−65 to +160</td>
<td>°C</td>
</tr>
<tr>
<td>Lead Soldering Temperature (10 sec)</td>
<td>300</td>
<td>°C</td>
</tr>
<tr>
<td>Operating Ambient Temperature Range</td>
<td>−40 to +85</td>
<td>°C</td>
</tr>
</tbody>
</table>

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

NOTE: TA = Ambient Temperature

Table 3. ELECTRICAL CHARACTERISTICS (V+ = 5 V, C1 = C2 = 150 μF, Boost/FC = Open, COSC = 0 pF; inverter mode with test circuit as shown in Figure 3 unless otherwise noted. Temperature is over operating ambient temperature range unless otherwise noted.)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Units</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage</td>
<td>VS</td>
<td>Inverter: LV = Open, RL = 1 kΩ</td>
<td>3.0</td>
<td>5.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>Inverter: LV = GND, RL = 1 kΩ</td>
<td>1.5</td>
<td>5.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>Doubler: LV = OUT, RL = 1 kΩ</td>
<td>2.5</td>
<td>5.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>Supply Current</td>
<td>IS</td>
<td>BOOST/FC = open, LV = Open</td>
<td>0.09</td>
<td>0.5</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>BOOST/FC = V+, LV = Open</td>
<td>0.3</td>
<td>3</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>Output Current</td>
<td>IOUT</td>
<td>OUT is more negative than −4 V</td>
<td>100</td>
<td>mA</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Output Resistance</td>
<td>RO</td>
<td>I_L = 100 mA, C1 = C2 = 150 μF (Note 5)</td>
<td>4</td>
<td>7</td>
<td>Ω</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>BOOST/FC = V+ (C1, C2 ESR ≤ 0.5 Ω)</td>
<td>12</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Oscillator Frequency</td>
<td>FOSC</td>
<td>BOOST/FC = Open</td>
<td>5</td>
<td>10</td>
<td>kHz</td>
<td></td>
</tr>
<tr>
<td>(Note 6)</td>
<td></td>
<td>BOOST/FC = V+</td>
<td>40</td>
<td>80</td>
<td></td>
<td></td>
</tr>
<tr>
<td>OSC Input Current</td>
<td>IOSC</td>
<td>BOOST/FC = Open</td>
<td>±1</td>
<td>±5</td>
<td>μA</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>BOOST/FC = V+</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Power Efficiency</td>
<td>PE</td>
<td>RL = 1 kΩ connected between V+ and OUT, TA = 25°C (Doubler)</td>
<td>96</td>
<td>98</td>
<td>%</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>RL = 500 Ω connected between GND and OUT, TA = 25°C (Inverter)</td>
<td>92</td>
<td>96</td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>I_L = 100 mA to GND, TA = 25°C (Inverter)</td>
<td>88</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Voltage Conversion Efficiency</td>
<td>VEFF</td>
<td>No load, TA = 25°C</td>
<td>99</td>
<td>99.9</td>
<td>%</td>
<td></td>
</tr>
</tbody>
</table>

4. In Figure 3, test circuit capacitors C1 and C2 are 150 μF and have 0.2 Ω maximum ESR. Higher ESR levels may reduce efficiency and output voltage.
5. The output resistance is a combination of the internal switch resistance and the external capacitor ESR. For maximum voltage and efficiency keep external capacitor ESR under 0.2 Ω.
6. FOSC is tested with COSC = 100 pF to minimize test fixture loading. The test is correlated back to COSC = 0 pF to simulate the capacitance at OSC when the device is inserted into a test socket without an external COSC.
Voltage Inverter

Figure 3. Test Circuit

TYPICAL OPERATING CHARACTERISTICS
(Typical characteristic curves are generated using the test circuit in Figure 3. Inverter test conditions are: $V_+ = 5 \text{ V}$, $LV = \text{GND}$, BOOST/FC = Open and $T_A = 25^\circ \text{C}$ unless otherwise indicated. Note that the charge–pump frequency is one–half the oscillator frequency.)

Figure 4. Supply Current vs. Input Voltage

Figure 5. Supply Current vs. Temperature (No Load)

Figure 6. Output Resistance vs. Input Voltage

Figure 7. Output Resistance vs. Temperature (50 \text{ \Omega} \text{ Load})
Figure 8. Inverted Output Voltage vs. Load, $V_+ = 5 \text{ V}$

Figure 9. Output Voltage Drop vs. Load Current

Figure 10. Oscillator Frequency vs. Supply Voltage

Figure 11. Oscillator Frequency vs. Supply Voltage

Figure 12. Supply Current vs. Oscillator Frequency
Application Information

Circuit Description and Operating Theory

The CAT660 switches capacitors to invert or double an input voltage.

Figure 13 shows a simple switch capacitor circuit. In position 1 capacitor C1 is charged to voltage V1. The total charge on C1 is $Q_1 = C_1 V_1$. When the switch moves to position 2, the input capacitor C1 is discharged to voltage V2. After discharge, the charge on C1 is $Q_2 = C_1 V_2$.

The charge transferred is:

$$\Delta Q = Q_1 - Q_2 = C_1 \times (V_1 - V_2)$$

If the switch is cycled “F” times per second, the current (charge transfer per unit time) is:

$$I = F \times \Delta Q = F \times C_1 \times (V_1 - V_2)$$

Rearranging in terms of impedance:

$$I = \frac{(V_1 - V_2)}{(1/FC_1)} = \frac{V_1 - V_2}{REQ}$$

The $1/FC_1$ term can be modeled as an equivalent impedance $REQ$. A simple equivalent circuit is shown in Figure 14. This circuit does not include the switch resistance nor does it include output voltage ripple. It does allow one to understand the switch−capacitor topology and make prudent engineering tradeoffs.

For example, power conversion efficiency is set by the output impedance, which consists of $REQ$ and switch resistance. As switching frequency is decreased, $REQ$, the $1/FC_1$ term, will dominate the output impedance, causing higher voltage losses and decreased efficiency. As the frequency is increased quiescent current increases. At high frequency this current becomes significant and the power efficiency degrades.

The oscillator is designed to operate where voltage losses are a minimum. With external 150 µF capacitors, the internal switch resistances and the Equivalent Series Resistance (ESR) of the external capacitors determine the effective output impedance.

A block diagram of the CAT660 is shown in Figure 15. The CAT660 is a replacement for the MAX660 and the LTC660.

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![Figure 13. Switched−Capacitor Building Block](image1)

![Figure 14. Switched−Capacitor Equivalent Circuit](image2)
**Oscillator Frequency Control**

The switching frequency can be raised, lowered or driven from an external source. Figure 16 shows a functional diagram of the oscillator circuit.

The CAT660 oscillator has four control modes:

<table>
<thead>
<tr>
<th>BOOST/FC Pin Connection</th>
<th>OSC Pin Connection</th>
<th>Nominal Oscillator Frequency</th>
</tr>
</thead>
<tbody>
<tr>
<td>Open</td>
<td>Open</td>
<td>10 kHz</td>
</tr>
<tr>
<td>BOOST/FC = V+</td>
<td>Open</td>
<td>80 kHz</td>
</tr>
<tr>
<td>Open or BOOST/FC = V+</td>
<td>External Capacitor</td>
<td>-</td>
</tr>
<tr>
<td>Open</td>
<td>External Clock</td>
<td>Frequency of external clock</td>
</tr>
</tbody>
</table>

If BOOST/FC and OSC are left floating (Open), the nominal oscillator frequency is 10 kHz. The pump frequency is one-half the oscillator frequency.

By connecting the BOOST/FC pin to V+, the charge and discharge currents are increased, and the frequency is increased by approximately 8 times. Increasing the frequency will decrease the output impedance and ripple currents. This can be an advantage at high load currents. Increasing the frequency raises quiescent current but allows smaller capacitance values for C1 and C2.

If pin 7, OSC, is loaded with an external capacitor the frequency is lowered. By using the BOOST/FC pin and an external capacitor at OSC, the operating frequency can be set.

Note that the frequency appearing at CAP+ or CAP− is one-half that of the oscillator.

Driving the CAT660 from an external frequency source can be easily achieved by driving Pin 7 and leaving the BOOST pin open, as shown in Figure 16. The output current from Pin 7 is small, typically 1 µA to 8 µA, so a CMOS can drive the OSC pin. For 5 V applications, a TTL logic gate can be used if an external 100 kΩ pull-up resistor is used as shown in Figure 17.
Capacitor Selection

Low ESR capacitors are necessary to minimize voltage losses, especially at high load currents. The exact values of C1 and C2 are not critical but low ESR capacitors are necessary.

The ESR of capacitor C1, the pump capacitor, can have a pronounced effect on the output. C1 currents are approximately twice the output current and losses occur on both the charge and discharge cycle. The ESR effects are thus multiplied by four. A 0.5 Ω ESR for C1 will have the same effect as a 2 Ω increase in CAT660 output impedance.

Output voltage ripple is determined by the value of C2 and the load current. C2 is charged and discharged at a current roughly equal to the load current. The internal switching frequency is one–half the oscillator frequency.

\[ VRIPPLE = I_{OUT} \times (\frac{F_{OSC}}{C_2}) + I_{OUT} \times ESR_{C2} \]

For example, with a 10 kHz oscillator frequency (5 kHz switching frequency), a 150 μF C2 capacitor with an ESR of 0.2 Ω and a 100 mA load peak–to–peak ripple voltage is 87 mV.

### Table 5. VRIPPLE vs. FOSC

<table>
<thead>
<tr>
<th>VRIPPLE (mV)</th>
<th>IOUT (mA)</th>
<th>FOSC (kHz)</th>
<th>C2 (μF)</th>
<th>C2 ESR (Ω)</th>
</tr>
</thead>
<tbody>
<tr>
<td>87</td>
<td>100</td>
<td>10</td>
<td>150</td>
<td>0.2</td>
</tr>
<tr>
<td>28</td>
<td>100</td>
<td>80</td>
<td>150</td>
<td>0.2</td>
</tr>
</tbody>
</table>

### Figure 16. Oscillator

### Figure 17. External Clocking
Capacitor Suppliers
The following manufacturers supply low-ESR capacitors:

<table>
<thead>
<tr>
<th>Manufacturer</th>
<th>Capacitor Type</th>
<th>Phone</th>
<th>WEB</th>
<th>Email</th>
<th>Comments</th>
</tr>
</thead>
<tbody>
<tr>
<td>AVX/Kyocera</td>
<td>TPS/TPS3</td>
<td>843–448–9411</td>
<td><a href="http://www.avxcorp.com">www.avxcorp.com</a></td>
<td><a href="mailto:avx@avxcorp.com">avx@avxcorp.com</a></td>
<td>Tantalum</td>
</tr>
<tr>
<td>Vishay/Sprague</td>
<td>595</td>
<td>402–563–6866</td>
<td><a href="http://www.vishay.com">www.vishay.com</a></td>
<td>–</td>
<td>Aluminum</td>
</tr>
<tr>
<td>Sanyo</td>
<td>MV–AX, UGX</td>
<td>619–661–6835</td>
<td><a href="http://www.sanyo.com">www.sanyo.com</a></td>
<td><a href="mailto:Svcsales@sanyo.com">Svcsales@sanyo.com</a></td>
<td>Aluminum</td>
</tr>
<tr>
<td></td>
<td>HC/HD</td>
<td></td>
<td></td>
<td></td>
<td>Aluminum</td>
</tr>
</tbody>
</table>

Capacitor manufacturers continually introduce new series and offer different package styles. It is recommended that before a design is finalized capacitor manufacturers should be surveyed for their latest product offerings.

Controlling Loss in CAT660 Applications
There are three primary sources of voltage loss:

1. Output resistance:
   \[ VLOSS = ILOAD \times ROUT \] where ROUT is the CAT660 output resistance and ILOAD is the load current.

2. Charge pump (C1) capacitor ESR:
   \[ VLOSSC1 = 4 \times ESRC1 \times ILOAD \] where ESRC1 is the ESR of capacitor C1.

3. Output or reservoir (C2) capacitor ESR:
   \[ VLOSSC2 = ESRC2 \times ILOAD \] where ESRC2 is the ESR of capacitor C2.

   Increasing the value of C2 and/or decreasing its ESR will reduce noise and ripple.

   The effective output impedance of a CAT660 circuit is approximately:
   \[ R_{circuit} \approx \frac{Rout 660}{ESRC1^2} + ESRC2 \]
Typical Applications

Voltage Inversion Positive-to-Negative

The CAT660 easily provides a negative supply voltage from a positive supply in the system. Figure 18 shows a typical circuit. The LV pin may be left floating for positive input voltages at or above 3.3 V.

![Figure 18. Voltage Inverter](image)

Positive Voltage Doubler

The voltage doubler circuit shown in Figure 19 gives $V_{OUT} = 2 \times V_{IN}$ for input voltages from 2.5 V to 5.5 V.

![Figure 19. Voltage Doubler](image)
Precision Voltage Divider

A precision voltage divider is shown in Figure 20. With very light load currents under 100 nA, the voltage at pin 2 will be within 0.002% of V+/2. Output voltage accuracy decreases with increasing load.

![Figure 20. Precision Voltage Divider (Load ≤ 100 nA)](image)

Battery Voltage Splitter

Positive and negative voltages that track each other can be obtained from a battery. Figure 21 shows how a 9 V battery can provide symmetrical positive and negative voltages equal to one-half the battery voltage.

![Figure 21. Battery Splitter](image)
Cascade Operation for Higher Negative Voltages

The CAT660 can be cascaded as shown in Figure 22 to generate more negative voltage levels. The output resistance is approximately the sum of the individual CAT660 output resistance.

\[ V_{OUT} = -N \times V_{IN}, \] where N represents the number of cascaded devices.

**Figure 22. Cascading to Increase Output Voltage**

Parallel Operation

Paralleling CAT660 devices will lower output resistance. As shown in Figure 23, each device requires its own pump capacitor, C2, but the output reservoir capacitor is shared with all devices. The value of C2 should be increased by a factor of N, where N is the number of devices.

The output impedance of the combined CAT660’s is:

\[ R_{OUT} (\text{Of “N” CAT660’s}) = \frac{R_{OUT} (\text{Of the CAT660})}{N (\text{Number of devices})} \]

**Figure 23. Paralleling Devices Reduce Output Resistance**
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

SOIC–8, 150 mils
CASE 751BD
ISSUE O

DATE 19 DEC 2008

PIN # 1
IDENTIFICATION

TOP VIEW

SIDE VIEW

END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MS-012.

<table>
<thead>
<tr>
<th>SYMBOL</th>
<th>MIN</th>
<th>NOM</th>
<th>MAX</th>
</tr>
</thead>
<tbody>
<tr>
<td>A</td>
<td>1.35</td>
<td></td>
<td>1.75</td>
</tr>
<tr>
<td>A1</td>
<td>0.10</td>
<td></td>
<td>0.25</td>
</tr>
<tr>
<td>b</td>
<td>0.33</td>
<td></td>
<td>0.51</td>
</tr>
<tr>
<td>c</td>
<td>0.19</td>
<td></td>
<td>0.25</td>
</tr>
<tr>
<td>D</td>
<td>4.80</td>
<td></td>
<td>5.00</td>
</tr>
<tr>
<td>E</td>
<td>5.80</td>
<td></td>
<td>6.20</td>
</tr>
<tr>
<td>E1</td>
<td>3.80</td>
<td></td>
<td>4.00</td>
</tr>
<tr>
<td>e</td>
<td></td>
<td>1.27</td>
<td>BSC</td>
</tr>
<tr>
<td>h</td>
<td>0.25</td>
<td></td>
<td>0.50</td>
</tr>
<tr>
<td>L</td>
<td>0.40</td>
<td></td>
<td>1.27</td>
</tr>
<tr>
<td>θ</td>
<td>0°</td>
<td></td>
<td>8°</td>
</tr>
</tbody>
</table>

DOCUMENT NUMBER: 98AON34272E
DESCRIPTION: SOIC 8, 150 MILS

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